1. Product Change Notification [PCN] basic data

Customer		Name Customer:	
		Contact Email address:	

1.1 Co.		Site submitting the change:		Melexis Sofia			
		Affected site(s):	Melexis Supplier				

1.2 PCN No.	MCM-4883
1.3 Title of PCN	Qualification of Amkor Technology Malaysia - package SOIC8 (MLX81106 & MLX81108)
1.4 Product Category	Active Components - Integrated Circuits
1.5 Issue date	**27-Nov-2020**

1.6 PCN revision history (optional)	1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)
V1.0	28-May-2020	Initial PCN
V2.0	27-Nov-2020	Final PCN

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	Lisa Vanheerswynghels
2.1.2 Phone	+32 57 22 62 07

2.1.3 Email	pcn_mlx@melexis.com

2.2 Team supplier (optional)		
2.2.1 Name (optional)	**2.2.2 Phone (optional)**	**2.2.3 Email (optional)**

3. Changes			
No.	**3.0 Ident**	**3.1 Category**	**3.2 Type of change**
#1	SEM-PA-18	PROCESS - ASSEMBLY	Move all or parts of production to a different assembly site.
#2	SEM-PA-19	PROCESS - ASSEMBLY	Die scribe or separation
#3			
#4			
#5			

4. Description of change		
	Old	**New**
Description #1	Current assembly source is AMKOR Philippines (ATP)	Future assembly sources will be AMKOR Malaysia (ATM) + AMKOR Philippines (ATP)
Description #2	Die sawing method: Single	Die sawing method: Dual [at AMKOR Malaysia (ATM)] + die sawing method: Single [at AMKOR

Description #3		
Description #4		
Description #5		
4.6 Anticipated impact on form, fit, function, reliability or processability?	- Based on Risk Assessment including AEC-Q100 and ZVEI guidelines	
4.7 Reference parts with customer number (optional)		

5. Reason / motivation for change

5.1 Motivation	As a responsible and future oriented player, Melexis is protecting it`s customers. This includes to secure the supply chain against environmental and/or material based events (contingency plan). The increase in business leads to package demand beyond Amkor Philippines capability.
5.2 Additional explanation (optional)	Please take notice that currently there is another change ongoing and communicated already to you. The scope of this change is: Wafer fab location: X-fab Kuching (Sarawak / Malaysia) --> Wafer fab location: X-fab Corbeil (France / Europe) + X-fab Kuching (Sarawak / Malaysia) - active second source waferfab foundry Corbeil (MCM-7866) - active second source probing site Corbeil and active second source waferfab foundry Corbeil (MCM-7873)

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by lot number and datecode through the Melexis ERP system.

7. Timing / schedule

7.1 Date of qualification results	Available	
7.2 Last order date (optional)		
7.3 Last delivery date (optional)		
7.4 Intended start of delivery	Q3 2021	Please contact your Customer Relations responsible for detailed information
7.5 Qualification samples available?	Available	
	Samples can be requested through pcn_mlx@melexis.com	
7.6 Customer feedback required until	14-Dec-2020	Please provide your initial feedback through the 'Customer Feedback' sheet as acknowledgement

8. Qualification / validation

8.1 Description (e.g. qualification or validation plan/report ...)	- Based on Risk Assessment including AEC-Q100 and ZVEI guidelines - see attached qualification plan			
8.2 Qualification report and qualification results	Available (see attachment)	issue date		0

9. Input to customer for risk assessment process

- No change in Bill Of Material
- No change in Bill Of Process
- the validation and qualification acc. to AEC-Q100 and ZVEI guidelines has been closed successfully
- see the ZVEI Delta Qualification Matrix for this change

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

ZVEI Delta Qualification Matrix_MLX81106_08_SOIC8 (1).pdf
MCM4883 final PCN SOIC8 GR_ATM_24Nov2020.pdf
PQR2020_09_MLX81108_81106_SOIC8_ATM.pdf

11. Affected parts									
11.1 Current						**11.2 New (if applicable)**			
11.1.1 Customer Part No.	**11.1.2 Supplier Part Name**	11.1.3 Supplier Part No. (opt)	**11.1.4 Pkg Name**	11.1.5 Part Descr (opt)	11.1.6 Addtl Part Info (opt)	**11.2.2 Supplier Part Name**	11.2.3 Supplier Part No. (opt)	**11.2.4 Pkg Name**	11.2.6 Addtl Part Info (opt)
N/A	MLX81106KDC-CAA-000-RE		SOIC8.GR						
N/A	MLX81108KDC-CAE-000-RE		SOIC8.GR						
N/A	MLX81108KDC-CAA-006-RE		SOIC8.GR						
N/A	MLX81108KDC-CAE-000-SP		SOIC8.GR						